PCN Numb		ber:	20170615006A					P	CN Date:	Sept. 6, 2017			
Title: Qualification of Ad				f Add	dditional Assembly site for select Devices								
Customer		r	PCN /	Mana	anager E		Dept:	Quality Serv	Quality Services				
Contact: Proposed Date:		1 st Ship	s		Sept. 19, 2017		Estim				Provided upon Request	١	
-	ange T	ype:								·			
\square	· · ·		[Assembly]		Materials		
	Design						Specification]	Mechanical Specificati		
Test Site			to		Packing/Shipping/Labeling Wafer Bump Material]	Test Proc			
┝┝┥	Wafer Bump Site Wafer Fab Site					Wafer Fab Materials]	Wafer Fa	mp Process		
	war				Part number char						Walchia	01100000	
							CN Det						
De	scripti	on of Cha	nge:										
Revision A is to announce the <u>addition</u> of new devices that were not included on the original PCN notification. These new devices are highlighted and bolded in the device list below. The expected first shipment date for these new devices will be 90 days from this notice for these newly added devices only. Texas Instruments is pleased to announce the qualification of PTI as an additional Assembly site for the devices listed below. There are no significant differences in devices built between the two assembly sites.													
Reason for Change:													
Со	Continuity of Supply												
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):													
No	ne												
		-	on M	late		l Declarat							
the N		mpact to Material aration	product Upon pr			oduction da	Declarations or Product Content reports are driven from ion data and will be available following the production release. oduction release the revised reports can be obtained from the website.						
Changes to product identification resulting from this PCN:													
	Assembly Site		Assembly Site Origin (22		.) Asseml	ssembly Country Code		_		embly City			
	JorJin		JJN			IN		TWN			NEW	TAIPEI CITY	
	PTI		PT2			F2		TWN			HSINCHU CITY		



Product Affected					
WL1801MODGBMOCR	WL1805MODGBMOCT	WL1831MODGBMOCT	WL1837MODGIMOC		
WL1801MODGBMOCR-WI	WL1807MODGIMOCR	WL1835MODGBMOCR	WL1837MODGIMOCR		
WL1801MODGBMOCT	WL1807MODGIMOCT	WL1835MODGBMOCT	WL1837MODGIMOCT		
WL1805MODGBMOCR	WL1831MODGBMOCR				



TI Information Selective Disclosure

Qualification Report

WL1835 MODULE - 2nd Source Plan - Assy site PTI

This Qualification report qualifies WL1801MOD, WL1805MOD & WL1835MOD for PTI Assembly

Product Attributes

Attributes	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC		
Assembly Site	PTI	PTI		
Package Family Module Module				
- QBS: Qual By Similarity				

- Qual Device is qualified at MSL LEVEL3-260C

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: WL1835MODGBMOC	QBS Device: WL1837MODGIMOC
PC	Preconditioning Level 3	MSL3, 260C reflow	1/50/0	1/230/0
TC	Temperature Cycle, -40/105	500cy	1/45/0	1/45/0
UHAST	Unbiased Temperature and Humidity, 85C/85%RH	500hr		1/45/0
LTSL	Low Temperature Storage Bake -40C	500hr		1/45/0
HTSL	High Temperature Bake 105C	500hr		1/45/0
VVF	Vibration Variance Frequency	20 - 2000 - 20 Hz Log sweep		1/5/0
CDM	ESD CDM	500V	1/3/0	1/3/0
HBM	ESD HBM	1000V	1/3/0	1/3/0

- Preconditioning was performed for Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
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